



ASC20N1200D88

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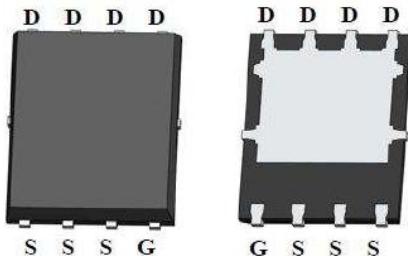
1200V N-Channel MOSFET

Description

Silicon Carbide (SiC) MOSFET use a completely new technology that provide superior switching performance and higher reliability compared to Silicon. In addition, the low ON resistance and compact chip size ensure low capacitance and gate charge. Consequently, system benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size.

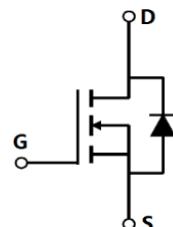
Features

- High Speed Switching with Low Capacitances
- High Blocking Voltage with Low RDS(on)
- Simple to drive with Standard Gate Drive
- EMI and performance balanced
- ROHS Compliant



Application

- LED lighting
- Charger
- Adapter
- TV power
- Telecom power
- Server power
- Solar/UP



Ordering Information

Part Number	Marking	Package	Packaging
ASC20N1200D88	ASC20N1200D88	PDFN8*8	Tube



ASC20N1200D88

Absolute Maximum Ratings(Tc=25°C)

Symbol	Parameter	Value	Unit
V _{DS}	Drain-Source Voltage	1200	V
I _D	Drain Current(continuous)at Tc=25°C	20	A
I _D	Drain Current(continuous)at Tc=100°C	10	A
I _{DM}	Drain Current (pulsed)	40	A
V _{GS}	Gate-Source Voltage	-10/+25	V
P _D	Power Dissipation T _C = 25°C	145	W
T _J , T _{Stg}	Junction and Storage Temperature Range	-55 to +150	°C

Electrical Characteristics(T_J = 25°C unless otherwise specified)**Typical Performance-Static**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
BV _{DS}	Drain-source Breakdown Voltage	I _D =250uA, V _{GS} =0V	1200			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =1200V, V _{GS} =0V, T _J =25°C			100	uA
I _{GSS}	Gate-body Leakage Current	V _{DS} =0V ; V _{GS} =10 to 20V			250	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D =5mA	2		4	V
R _{DS(on)}	Static Drain-source On Resistance	V _{GS} =20V, I _D =10A		130	160	mΩ
R _G	Gate Resistance	V _{GS} =0V,f=1MHz		5		Ω

Typical Performance-Dynamic

C _{iss}	Input Capacitance	V _{DS} =600V,f=1MHz,V _{GS} =0V		1000		pF
C _{oss}	Output Capacitance			70		pF
C _{rss}	Reverse Transfer Capacitance			15		pF
Q _g	Total Gate Charge	V _{DS} =600V, I _D =10A,V _{GS} =0~20V		48		nC
Q _{gs}	Gate-source Charge			22		nC
Q _{gd}	Gate-Drain Charge			10		nC
t _{d(on)}	Turn-on Delay Time	V _{DD} =600V,I _D =10A, V _{GS} =-4V~20V, R _G =0Ω,		22		ns
t _r	Rise Time			22		ns
t _{d(off)}	Turn-off Delay Time			20		ns
t _f	Fall Time			17		ns



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Typical Performance-Reverse Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_{FSD}	Forward Voltage	$V_{GS}=0V, I_F=10A, T_J=25^{\circ}C$	3		6	V
		$V_{GS}=0V, I_F=10A, T_J=150^{\circ}C$	3		6	V
t_{rr}	Reverse Recovery Time	$V_{GS}=0 V, I_F=10 A,$ $V_{DS} =600 V,$ $di/dt= 100 A/\mu s$		50		ns
	Reverse Recovery Charge			120		nC
I_{rrm}	Peak Reverse Recovery Current			5		A

Thermal Characteristics

Symbol	Parameter	Value.	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.86	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Case	62	°C/W

The values are based on the junction-to case thermal impedance which is measured with the device mounted to a large heat sink assuming maximum junction temperature of $T_j(max)=150^{\circ}C$

Electrical Characteristics

Figure 1: Output characteristics ($T_J = 25^\circ\text{C}$)

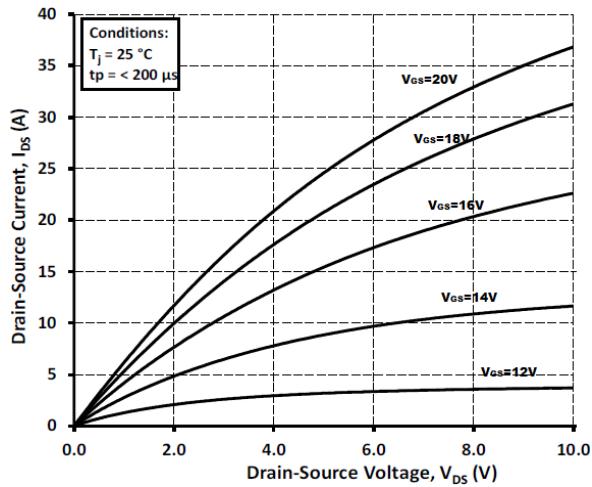


Figure 2: Output characteristics ($T_J = 150^\circ\text{C}$)

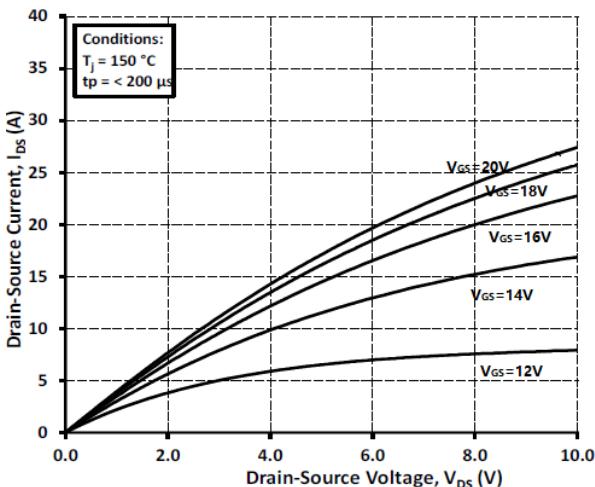


Figure 3: Transfer characteristics

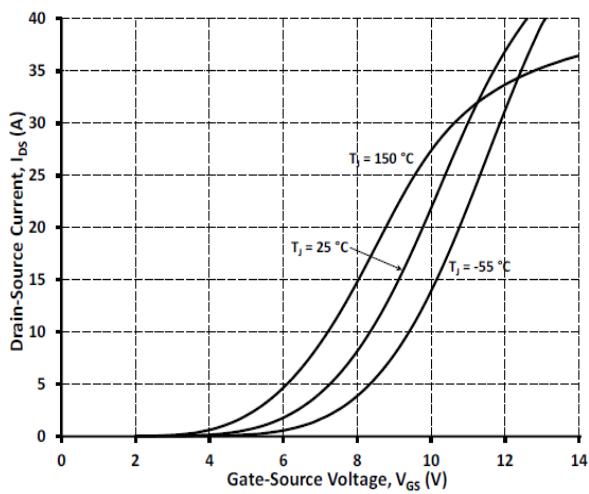


Figure 4 Normalized $R_{DS(on)}$ vs. Temperature

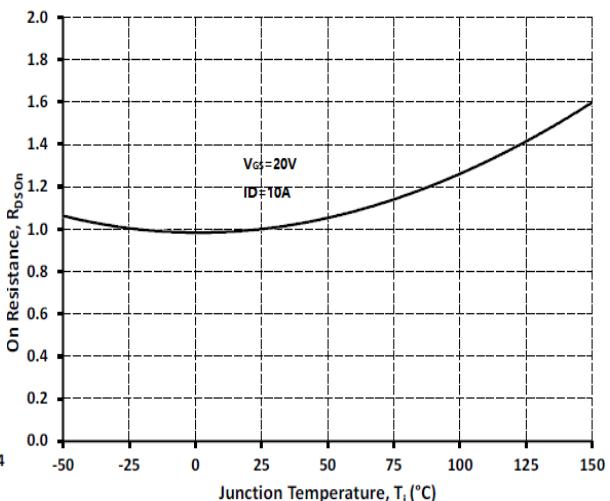


Figure 5: Power dissipation

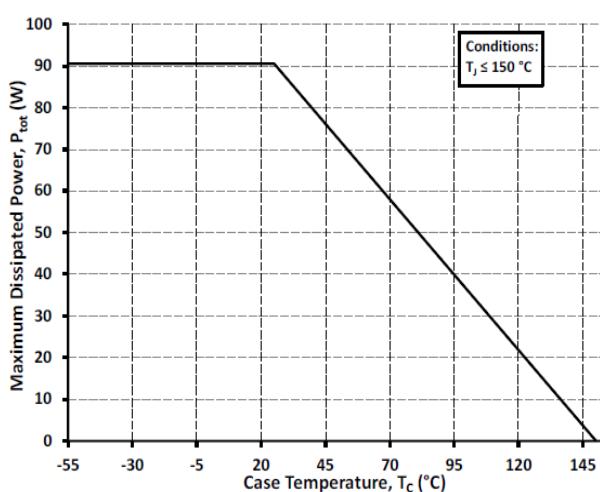


Figure 6: Gate charge vs gate-source voltage

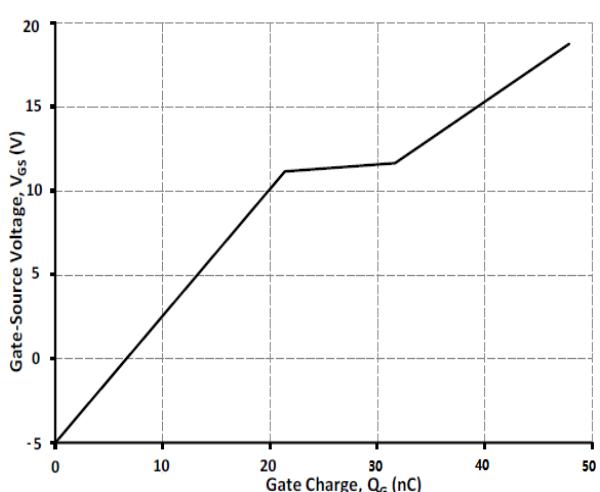


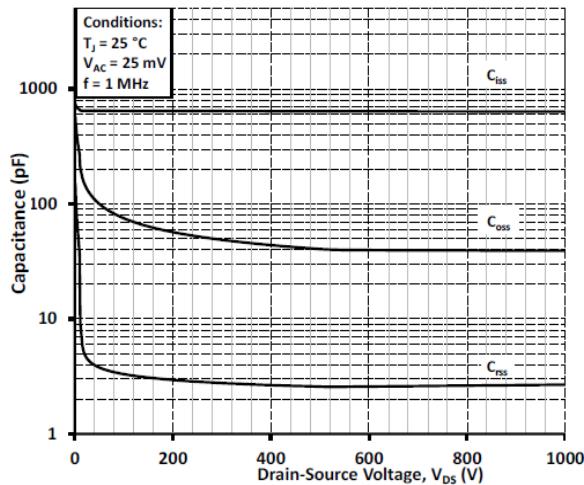
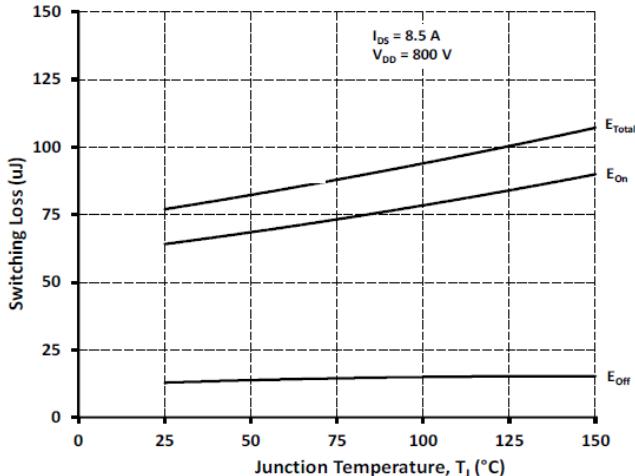
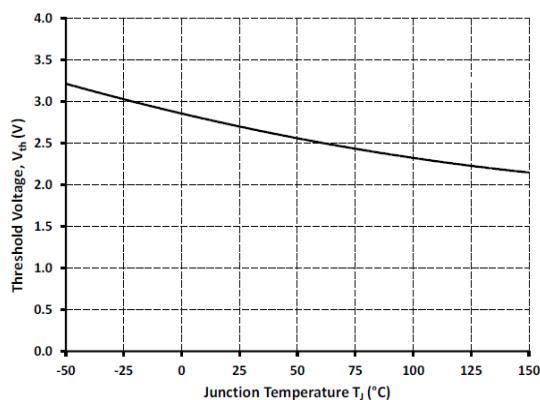
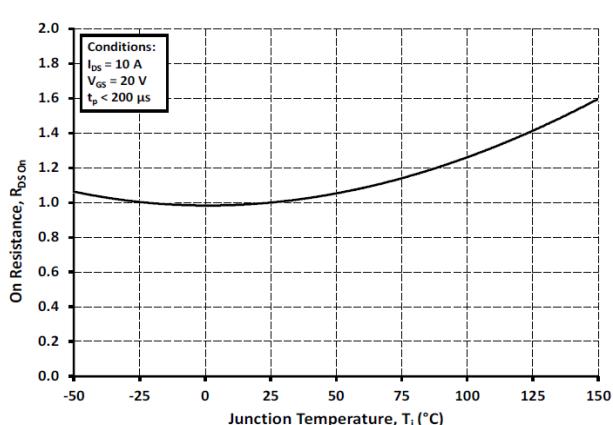
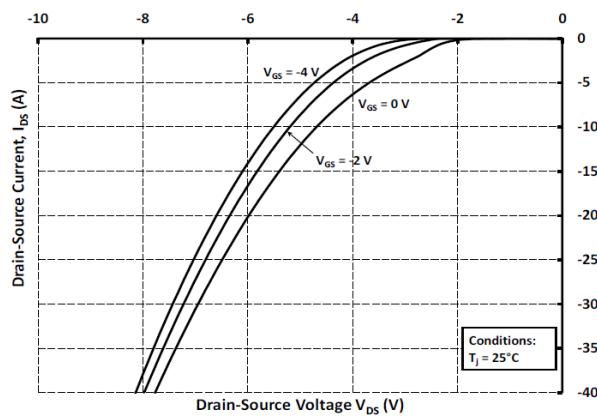
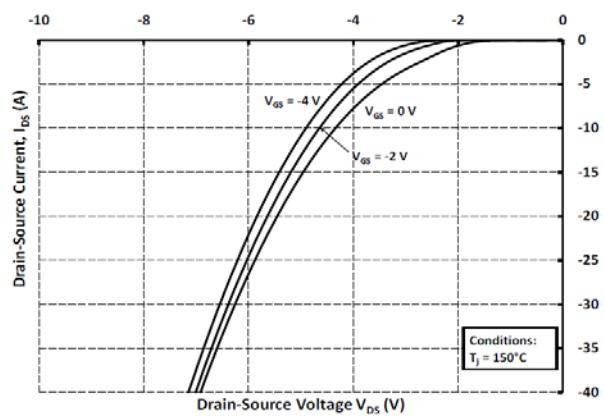
Figure 7: Capacitance variations

Figure 8: Switching energy vs. drain current

Figure 9: Normalized V_{th} vs. T_J

Figure 10: Normalized $R_{ds(on)}$ vs. T_J

Figure 11: Body diode characteristics
 $(T_J = 25^\circ\text{C})$

Figure 12: Body diode characteristics
 $(T_J = 150^\circ\text{C})$


Figure 15: Safe operating area

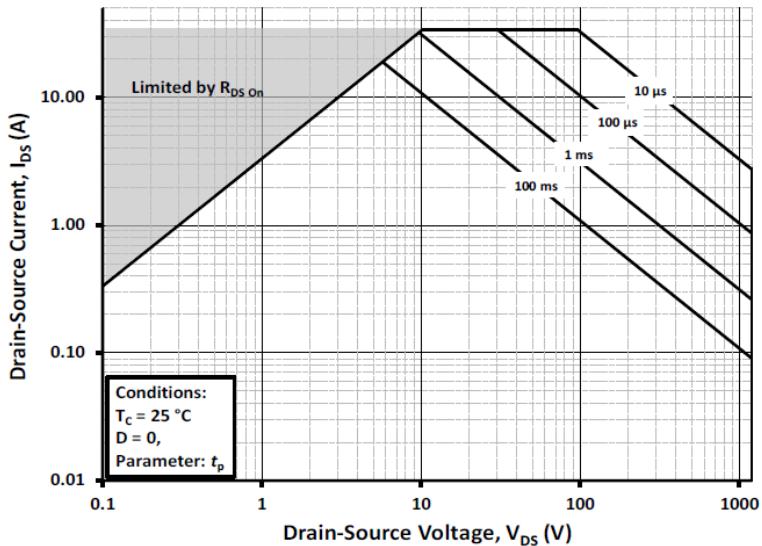
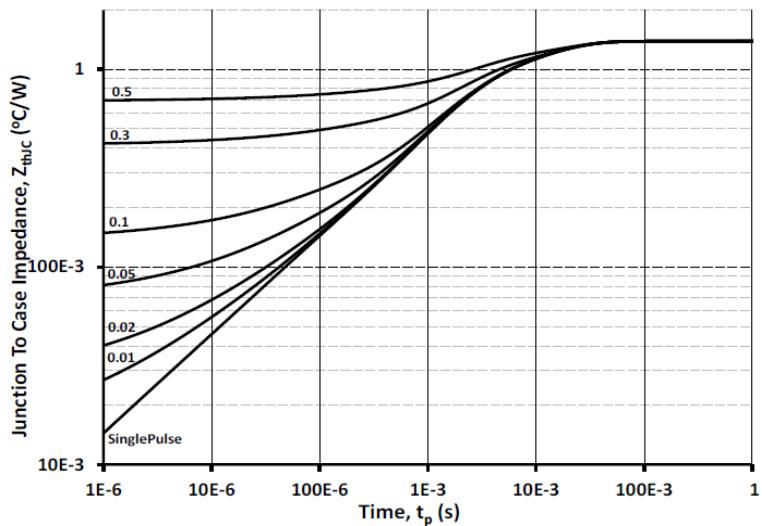
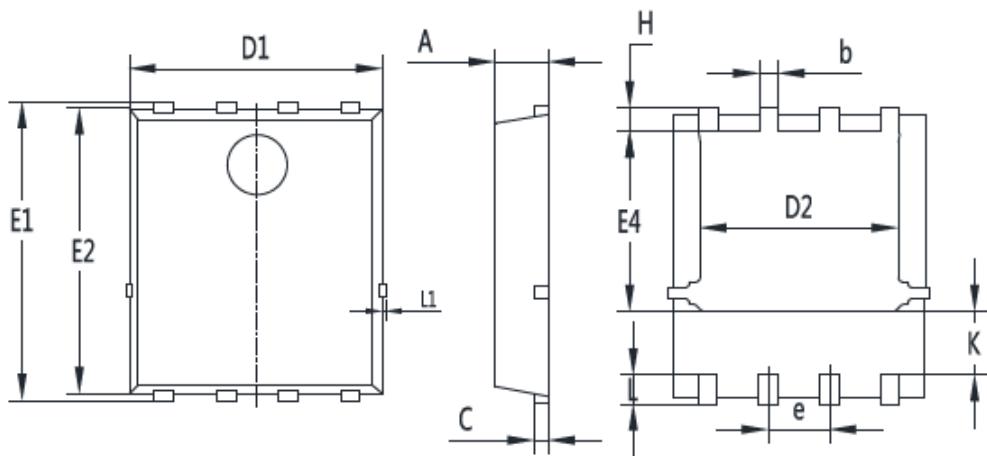


Figure 16: Thermal impedance



Package Drawing:**Dimensions (UNIT: mm)**

Symbol	mm		
	Min	Nom	Max
A	1.00	1.10	1.20
b	0.30	0.40	0.50
c	0.154	0.254	0.354
D1	5.00	5.20	5.40
D2	3.80	4.10	4.25
e	1.17	1.27	1.37
E1	5.95	6.15	6.35
E2	5.66	5.86	6.06
E4	3.52	3.72	3.92
H	0.40	0.50	0.60
L	0.30	0.60	0.70
L1	0.12 REF		
K	1.15	1.30	1.45